

DATA SHEET

SMD common mode chokes EMI-suppression products

Supersedes data of September 2004

2008 Sep 01

EMI-suppression products

SMD common mode chokes

SMD COMMON MODE CHOKES FOR EMI-SUPPRESSION

General data

| ITEM | SPECIFICATION |
|----------------|--|
| Strip material | copper (Cu), tin (Sn) plated |
| Solderability | "IEC 60068-2-58", Part 2, Test Ta, method 1 |
| Taping method | "IEC 60286-3", "EIA 481-1-A" and "EIA 481-2" |

Grades, parameters and type numbers

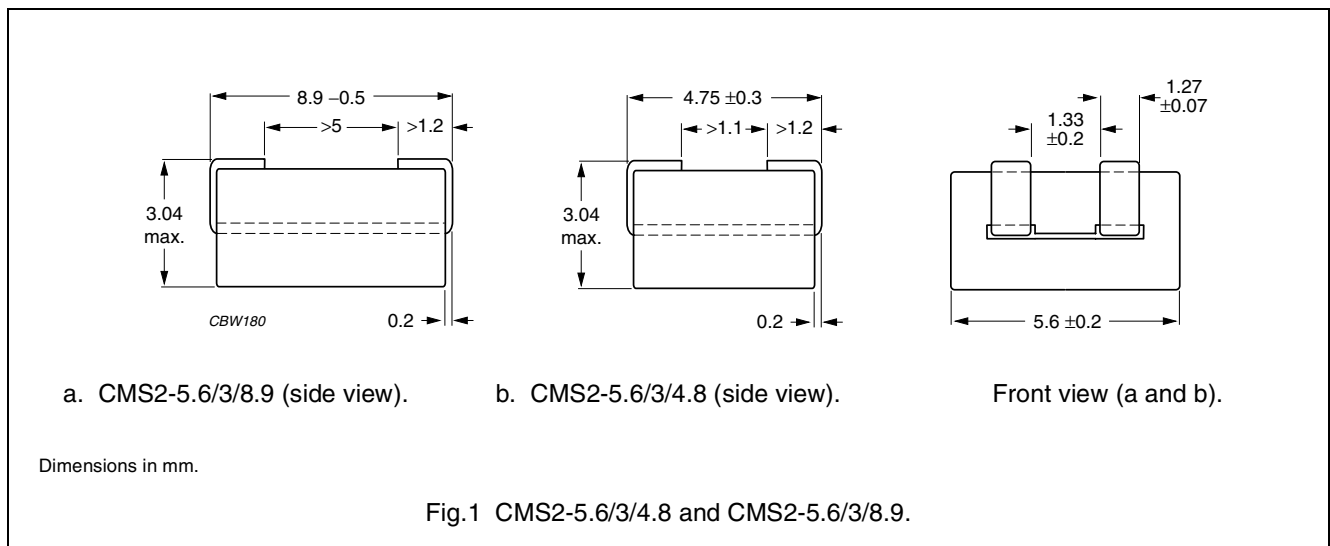
| GRADE | $ Z_{typ} ^{(1)}$ (Ω) | at f (MHz) | TYPE NUMBER |
|---|-----------------------------------|---------------|--------------------|
| CMS2-5.6/3/4.8; mass \approx0.3 g | | | |
| 4S2 | 21 | 25 | CMS2-5.6/3/4.8-4S2 |
| | 35 | 100 | |
| | 50 | 300 | |
| CMS2-5.6/3/8.9; mass \approx0.6 g | | | |
| 4S2 | 38 | 25 | CMS2-5.6/3/8.9-4S2 |
| | 60 | 100 | |

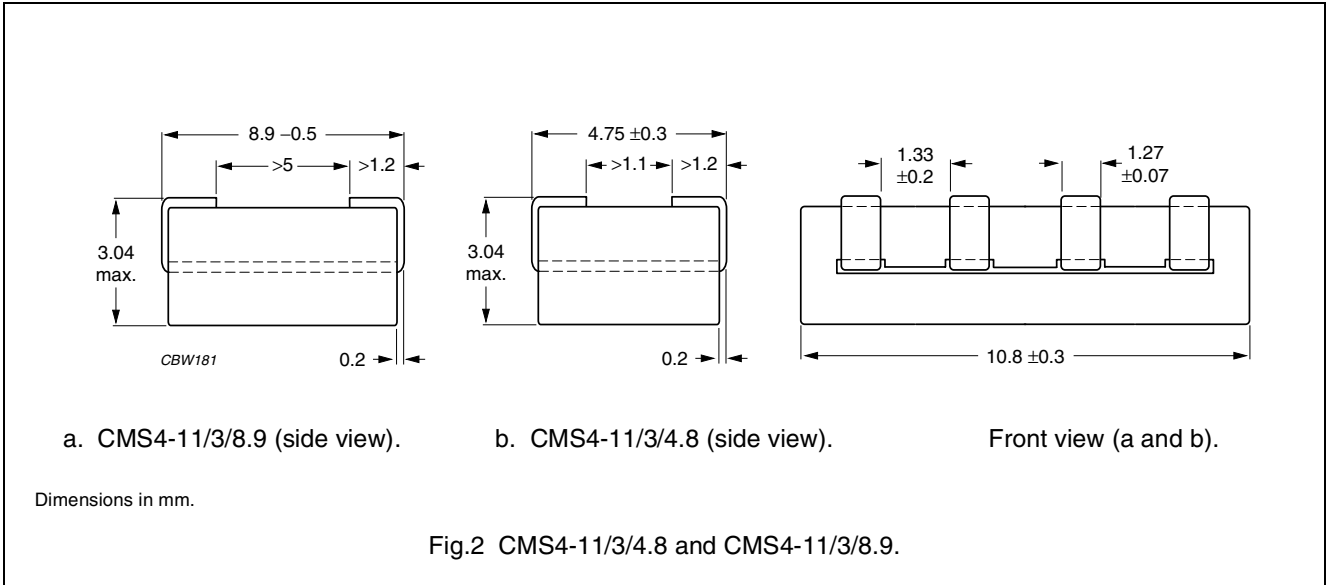
| GRADE | $ Z_{typ} ^{(1)}$ (Ω) | at f (MHz) | TYPE NUMBER |
|--|-----------------------------------|---------------|-------------------|
| CMS4-11/3/4.8; mass \approx0.6 g | | | |
| 4S2 inner channel | 12 | 25 | CMS4-11/3/4.8-4S2 |
| | 23 | 100 | |
| | 42 | 300 | |
| 4S2 outer channel | 15 | 25 | |
| | 30 | 100 | |
| | 50 | 300 | |
| CMS4-11/3/8.9; mass \approx1.1 g | | | |
| 4S2 inner channel | 23 | 25 | CMS4-11/3/8.9-4S2 |
| | 45 | 100 | |
| | 82 | 300 | |
| 4S2 outer channel | 27 | 25 | |
| | 58 | 100 | |
| | 97 | 300 | |

Note

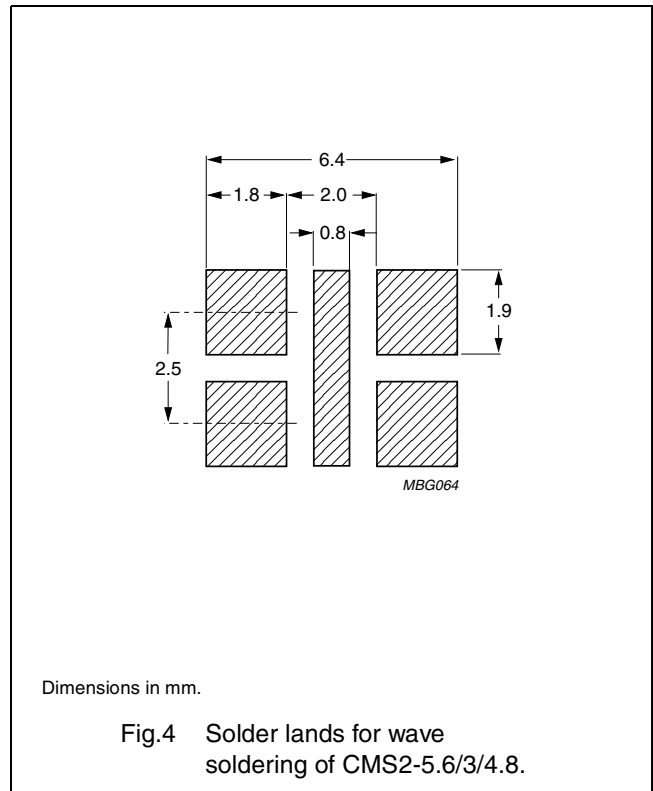
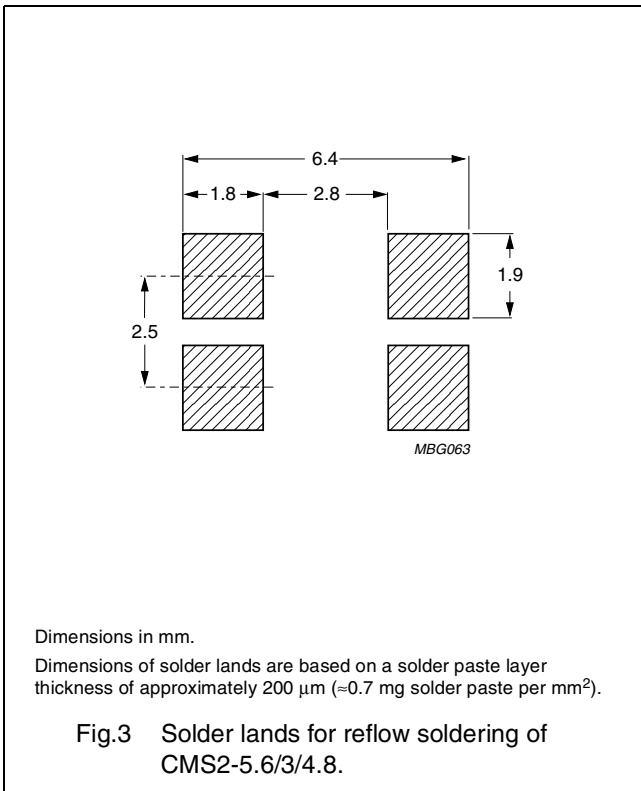
1. Typical values, $|Z|_{min}$ is -20% .
DC resistance < 0.6 m Ω .

Mechanical data



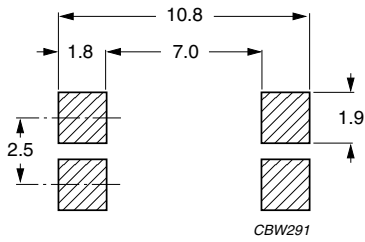


Recommended dimensions of solder lands



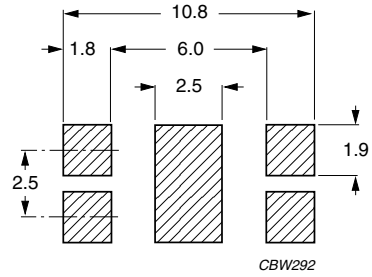
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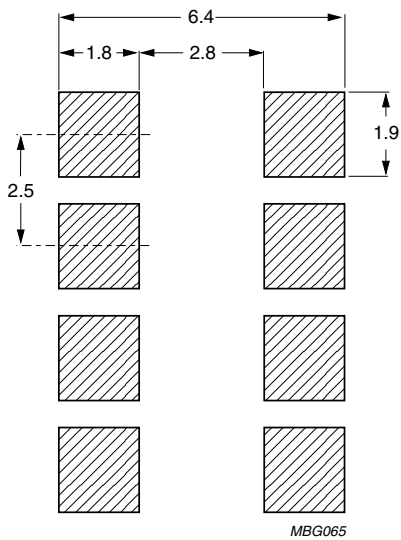
Dimensions in mm.
 Dimensions of solder lands are based on a solder paste layer thickness of approximately 200 μm (≈0.7 mg solder paste per mm²).

Fig.5 Solder lands for reflow soldering of CMS2-5.6/3/8.9.



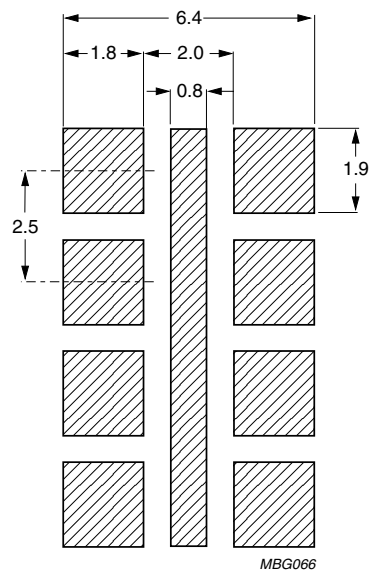
Dimensions in mm.

Fig.6 Solder lands for wave soldering of CMS2-5.6/3/8.9.



Dimensions in mm.
 Dimensions of solder lands are based on a solder paste layer thickness of approximately 200 μm (≈0.7 mg solder paste per mm²).

Fig.7 Solder lands for reflow soldering of CMS4-11/3/4.8.

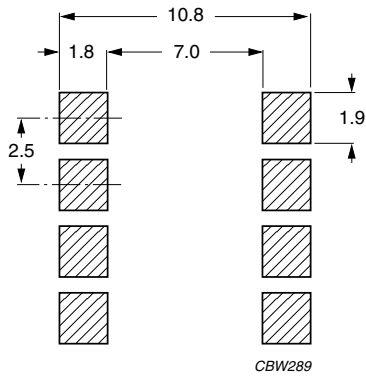


Dimensions in mm.

Fig.8 Solder lands for wave soldering of CMS4-11/3/4.8.

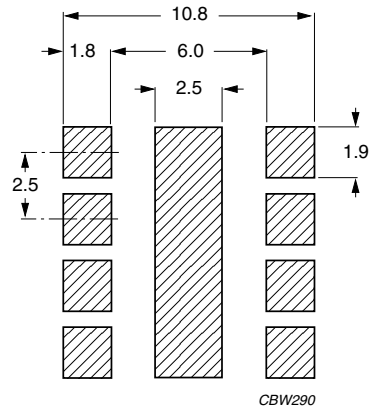
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Dimensions in mm.
 Dimensions of solder lands are based on a solder paste layer thickness of approximately 200 μm (≈ 0.7 mg solder paste per mm^2).

Fig.9 Solder lands for reflow soldering of CMS4-11/3/8.9.



Dimensions in mm.

Fig.10 Solder lands for wave soldering of CMS4-11/3/8.9.

Soldering profiles

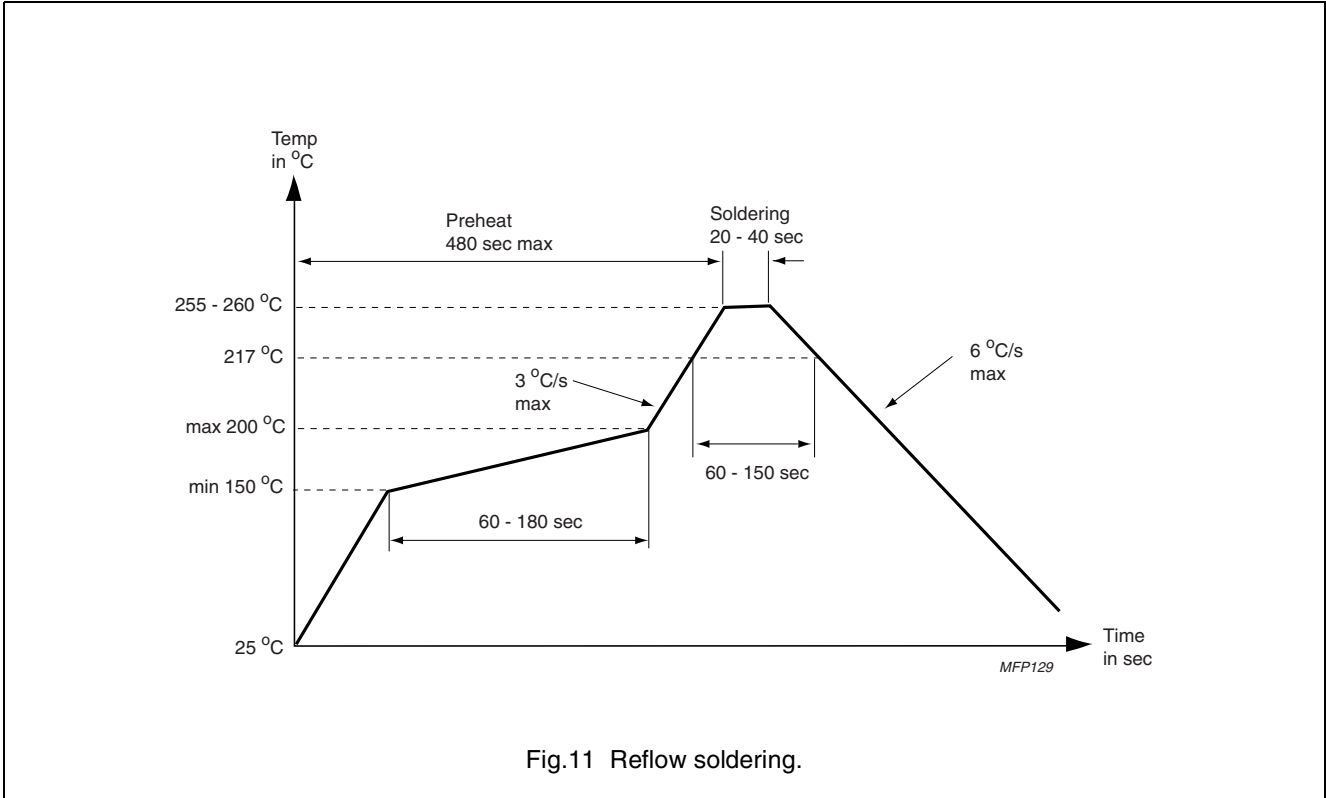
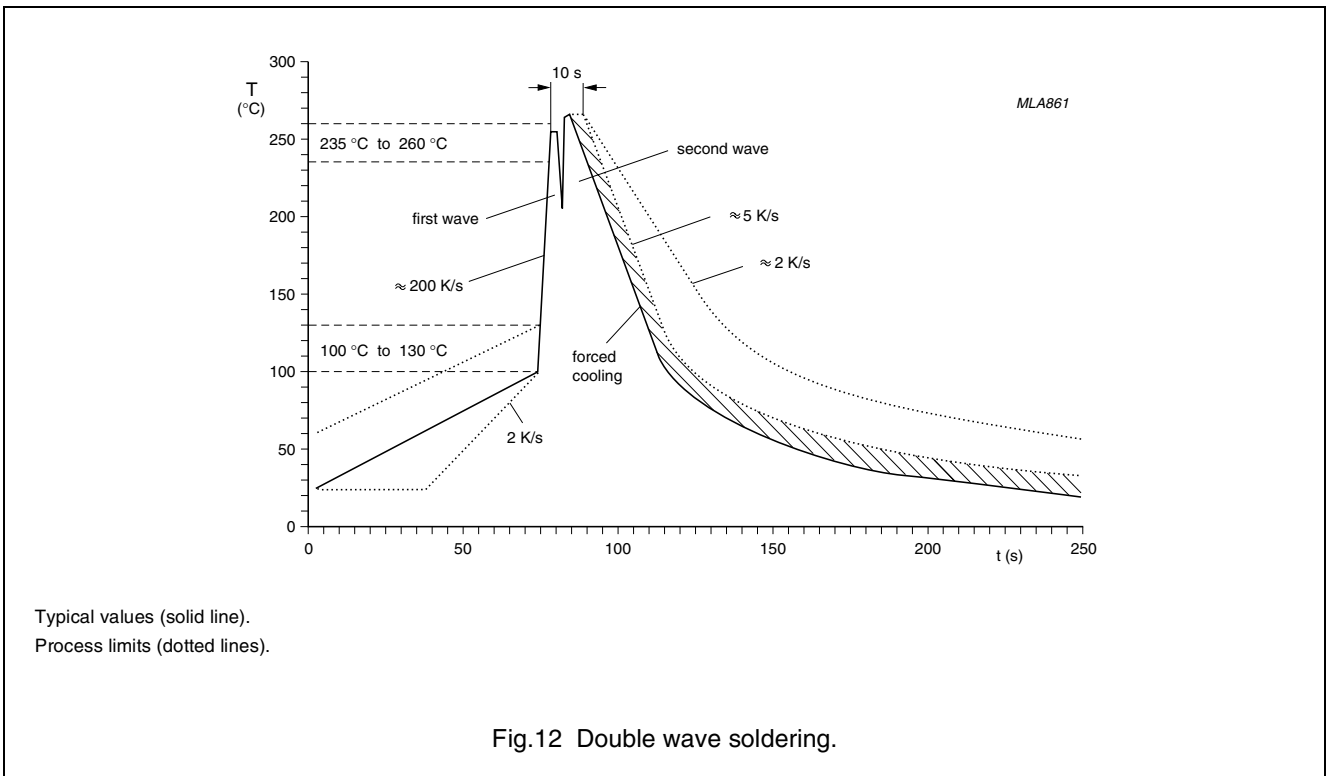


Fig.11 Reflow soldering.



Typical values (solid line).
Process limits (dotted lines).

Fig.12 Double wave soldering.

BLISTER TAPE AND REEL DIMENSIONS

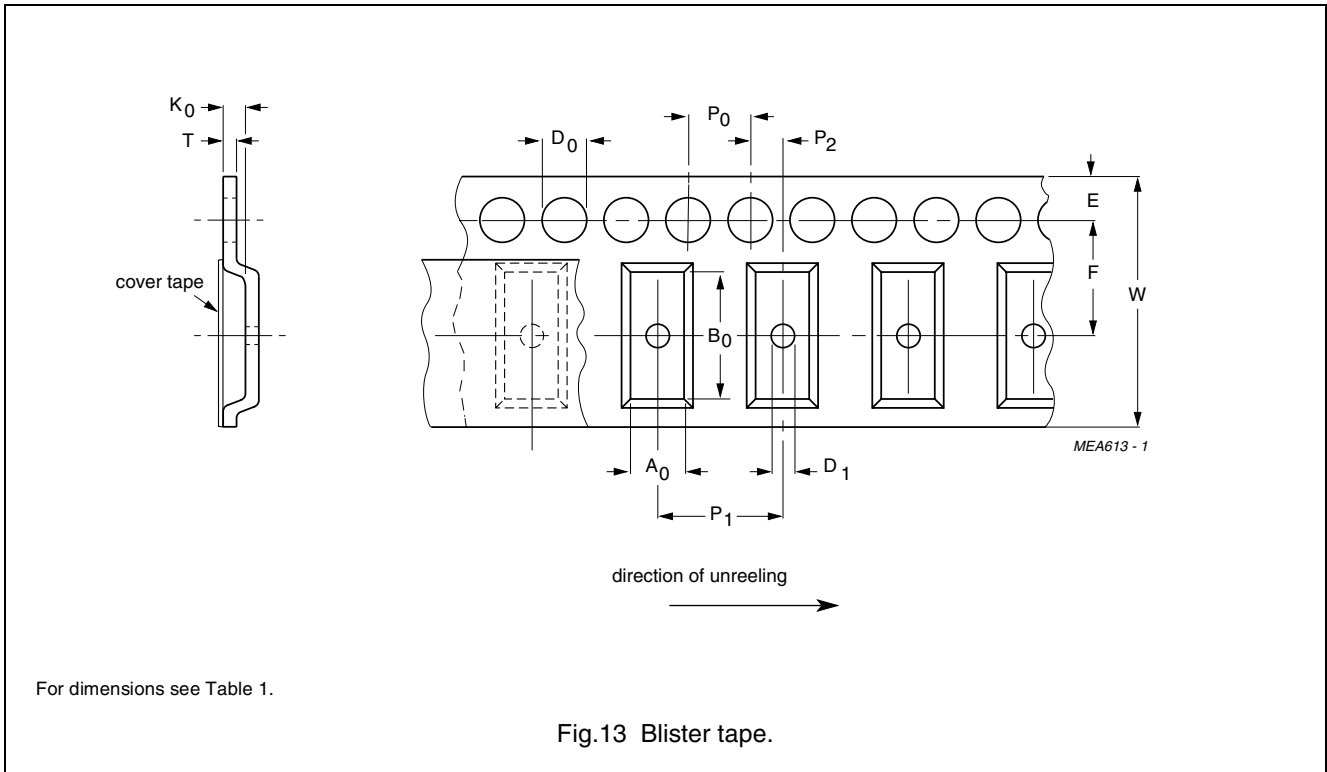


Table 1 Physical dimensions of blister tape; see Fig.13

| SIZE | DIMENSIONS (mm) | | | |
|-------|-----------------|----------------|----------------|---------------|
| | CMS2-5.6/3/4.8 | CMS2-5.6/3/8.9 | CMS2-5.6/3/8.9 | CMS4-11/3/8.9 |
| A_0 | 5.26 | 5.99 | 5.23 | 10.13 |
| B_0 | 6.07 | 9.09 | 11.18 | 11.56 |
| K_0 | 3.18 | 3.18 | 4.5 | 4.5 |
| T | 0.3 | 0.33 | 0.34 | 0.36 |
| W | 12 | 16 | 24 | 24 |
| E | 1.75 | 1.75 | 1.75 | 1.75 |
| F | 5.5 | 7.5 | 11.75 | 11.5 |
| D_0 | 1.5 | 1.5 | 1.5 | 1.5 |
| D_1 | ≥ 1.5 | ≥ 1.5 | ≥ 1.5 | ≥ 1.5 |
| P_0 | 4.0 | 4.0 | 4.0 | 4.0 |
| P_1 | 8.0 | 8.0 | 8.0 | 16.0 |
| P_2 | 2.0 | 2.0 | 2.0 | 2.0 |

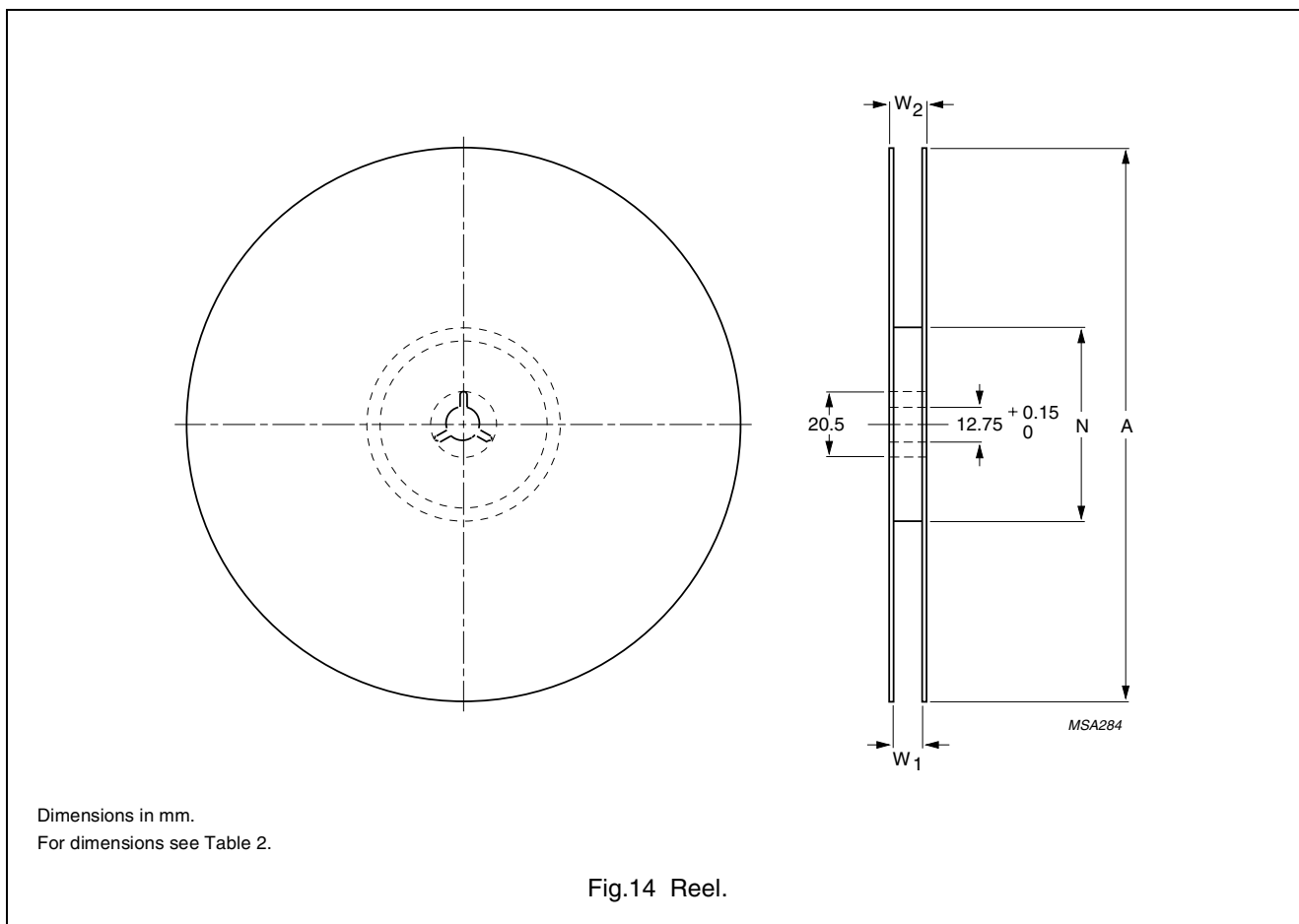


Table 2 Reel dimensions; see Fig.14

| SIZE | DIMENSIONS (mm) | | | |
|------|-----------------|--------|----------------|----------------|
| | A | N | W ₁ | W ₂ |
| 12 | 330 | 100 ±5 | 12.4 | ≤16.4 |
| 16 | 330 | 100 ±5 | 16.4 | ≤20.4 |
| 24 | 330 | 100 ±5 | 24.4 | ≤28.4 |

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DATA SHEET STATUS DEFINITIONS

| DATA SHEET STATUS | PRODUCT STATUS | DEFINITIONS |
|---------------------------|----------------|--|
| Preliminary specification | Development | This data sheet contains preliminary data. Ferroxcube reserves the right to make changes at any time without notice in order to improve design and supply the best possible product. |
| Product specification | Production | This data sheet contains final specifications. Ferroxcube reserves the right to make changes at any time without notice in order to improve design and supply the best possible product. |

DISCLAIMER

Life support applications — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Ferroxcube customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Ferroxcube for any damages resulting from such application.

PRODUCT STATUS DEFINITIONS

| STATUS | INDICATION | DEFINITION |
|------------------|---|--|
| Prototype |  | These are products that have been made as development samples for the purposes of technical evaluation only. The data for these types is provisional and is subject to change. |
| Design-in |  | These products are recommended for new designs. |
| Preferred | | These products are recommended for use in current designs and are available via our sales channels. |
| Support |  | These products are not recommended for new designs and may not be available through all of our sales channels. Customers are advised to check for availability. |